Final Product Change Notification

201911006F01

Issue Date: 06-Dec-2019
Effective Date: 05-Mar-2020

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

This notice is NXP Company Proprietary.

Change Category

- [X] Wafer Fab Process
- [ ] Wafer Fab Materials
- [ ] Wafer Fab Location
- [ ] Firmware
- [ ] Assembly Process
- [ ] Assembly Materials
- [ ] Assembly Location
- [ ] Other
- [ ] Product Marking
- [ ] Mechanical Specification
- [ ] Packing/Shipping/Labeling
- [ ] Test Location
- [ ]Test Process
- [ ] Test Equipment
- [ ] Design
- [ ] Errata
- [ ] Electrical spec./Test coverage

i.MXRT1064 Redistribution Layer Addition On Flash Die

Description of Change

NXP Semiconductors announces to add a RDL layer (Redistribution Layer) to separate the probing and wire bond pads on flash die for i.MXRT1064. The original bond pads and RDL pads are going to be on separate locations. Original bond pads are used for wafer test probing while RDL pads are for wire bonding process.

Reason for Change

This is to separate the probing and wire bond pads on flash die for manufacturing robustness.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 06-Mar-2020

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products
Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 05-Jan-2020.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

NXP Semiconductors
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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
MIMXRT1064CVL5A	935377468557	MIMXRT1064CVL5A	i.MXRT1064	SOT1546-2	LFBGA196	RFS	MCUs
MIMXRT1064DVL6A	935377469557	MIMXRT1064DVL6A	i.MXRT1064	SOT1546-2	LFBGA196	RFS	MCUs